



#### RE015-LF

- DIL-Labcard
- Epoxy fibre-glass 1.50 mm
- Single-sided 35 µm Cu
- Hot air leveling (HAL-Leadfree)
- 14 x 14 soldering pads 2.00 x 2.00 mm
- Hole spacing 2.54 x 2.54 mm
- Hole diameter 1.00 mm
- Size 40.00 x 40.50 mm